



6-Pin DIP Random-Phase Optoisolators Triac Driver Output (400 Volts Peak)

The MOC3020 Series consists of gallium arsenide infrared emitting diodes, optically coupled to a silicon bilateral switch.

- **To order devices that are tested and marked per VDE 0884 requirements, the suffix "V" must be included at end of part number. VDE 0884 is a test option.** They are designed for applications requiring isolated triac triggering.

Recommended for 115/240 Vac(rms) Applications:

- Solenoid/Valve Controls
- Lamp Ballasts
- Interfacing Microprocessors to 115 Vac Peripherals
- Motor Controls
- Static ac Power Switch
- Solid State Relays
- Incandescent Lamp Dimmers

MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
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INFRARED EMITTING DIODE

Reverse Voltage	V_R	3	Volts
Forward Current — Continuous	I_F	60	mA
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Negligible Power in Triac Driver Derate above 25°C	P_D	100 1.33	mW mW/°C

OUTPUT DRIVER

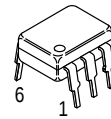
Off-State Output Terminal Voltage	V_{DRM}	400	Volts
Peak Repetitive Surge Current (PW = 1 ms, 120 pps)	I_{TSM}	1	A
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300 4	mW mW/°C

TOTAL DEVICE

Isolation Surge Voltage ⁽¹⁾ (Peak ac Voltage, 60 Hz, 1 Second Duration)	V_{ISO}	7500	Vac(pk)
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	330 4.4	mW mW/°C
Junction Temperature Range	T_J	-40 to +100	°C
Ambient Operating Temperature Range	T_A	-40 to +85	°C
Storage Temperature Range	T_{stg}	-40 to +150	°C
Soldering Temperature (10 s)	T_L	260	°C

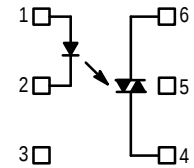
1. Isolation surge voltage, V_{ISO} , is an internal device dielectric breakdown rating. For this test, Pins 1 and 2 are common, and Pins 4, 5 and 6 are common.

MOC3021
MOC3022
MOC3023



STANDARD THRU HOLE

SCHEMATIC



1. ANODE
2. CATHODE
3. NC
4. MAIN TERMINAL
5. SUBSTRATE
DO NOT CONNECT
6. MAIN TERMINAL

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
INPUT LED					
Reverse Leakage Current ($V_R = 3\text{ V}$)	I_R	—	0.05	100	μA
Forward Voltage ($I_F = 10\text{ mA}$)	V_F	—	1.15	1.5	Volts
OUTPUT DETECTOR ($I_F = 0$ unless otherwise noted)					
Peak Blocking Current, Either Direction (Rated $V_{DRM}^{(1)}$)	I_{DRM}	—	10	100	nA
Peak On-State Voltage, Either Direction ($I_{TM} = 100\text{ mA Peak}$)	V_{TM}	—	1.8	3	Volts
Critical Rate of Rise of Off-State Voltage (Figure 7, Note 2)	dv/dt	—	10	—	$\text{V}/\mu\text{s}$
COUPLED					
LED Trigger Current, Current Required to Latch Output (Main Terminal Voltage = $3\text{ V}^{(3)}$)	I_{FT}	—	8	15	mA
MOC3021		—	—	10	
MOC3022		—	—	5	
MOC3023		—	—	—	
Holding Current, Either Direction	I_H	—	100	—	μA

1. Test voltage must be applied within dv/dt rating.
2. This is static dv/dt . See Figure 7 for test circuit. Commutating dv/dt is a function of the load-driving thyristor(s) only.
3. All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT} . Therefore, recommended operating I_F lies between max I_{FT} (15 mA for MOC3021, 10 mA for MOC3022, 5 mA for MOC3023) and absolute max I_F (60 mA).

TYPICAL ELECTRICAL CHARACTERISTICS

$T_A = 25^\circ\text{C}$

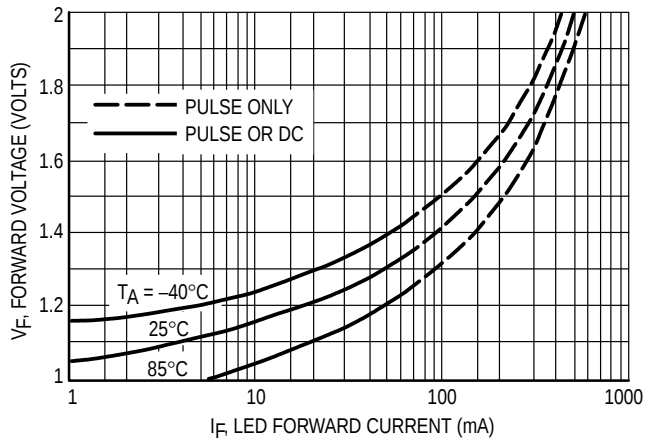


Figure 1. LED Forward Voltage versus Forward Current

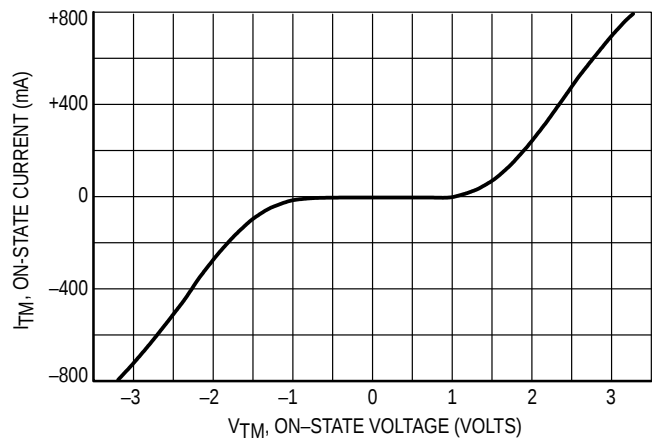


Figure 2. On-State Characteristics

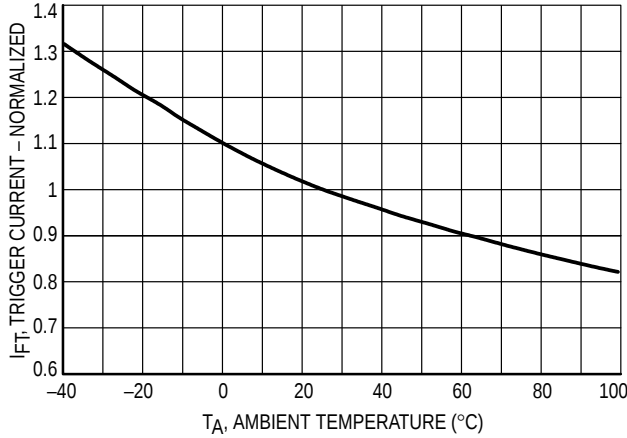


Figure 3. Trigger Current versus Temperature

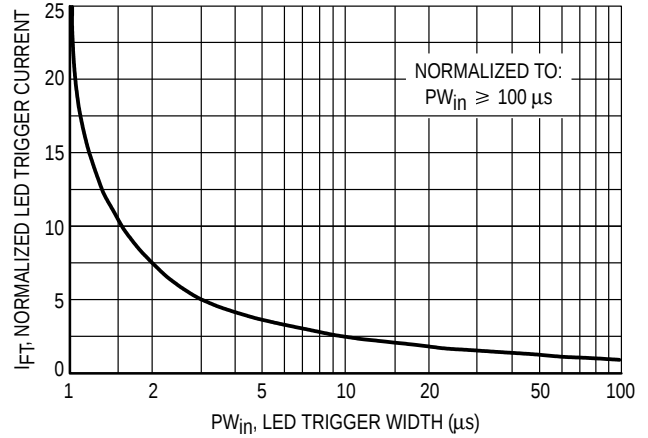


Figure 4. LED Current Required to Trigger versus LED Pulse Width

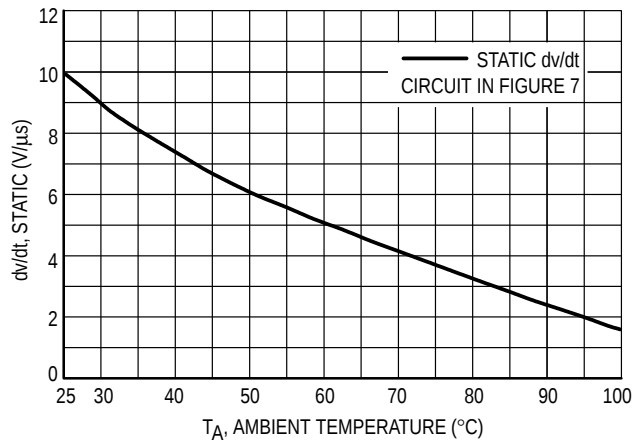


Figure 5. dv/dt versus Temperature

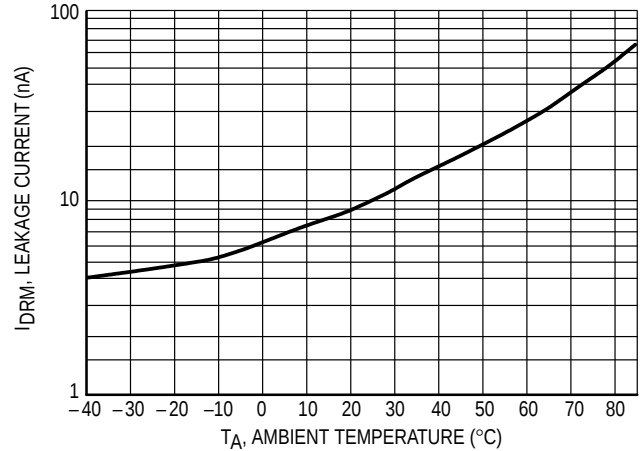


Figure 6. Leakage Current, I_{DRM} versus Temperature

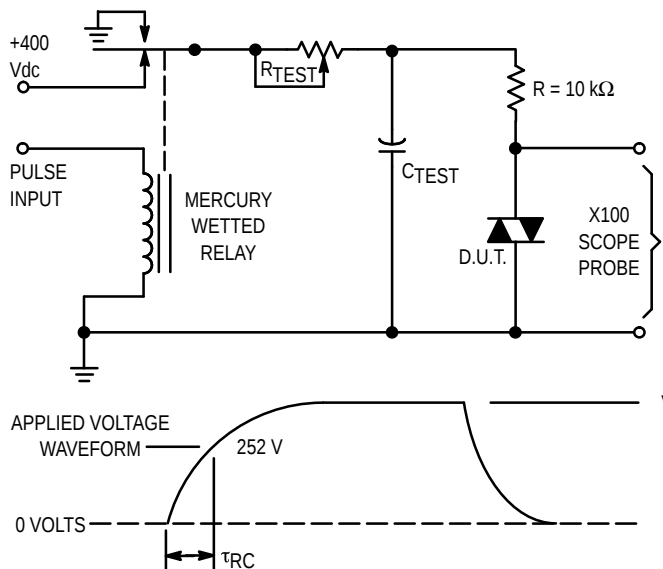
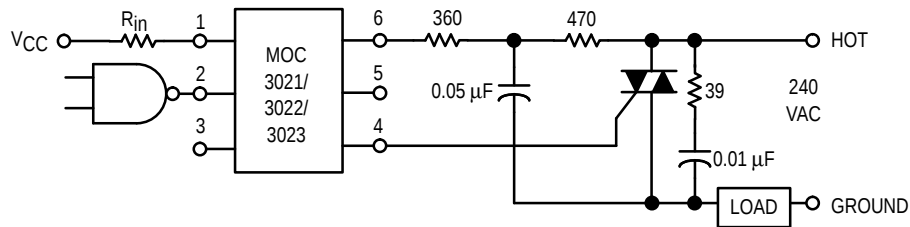


Figure 7. Static dv/dt Test Circuit

1. The mercury wetted relay provides a high speed repeated pulse to the D.U.T.
2. 100x scope probes are used, to allow high speeds and voltages.
3. The worst-case condition for static dv/dt is established by triggering the D.U.T. with a normal LED input current, then removing the current. The variable R_{TEST} allows the dv/dt to be gradually increased until the D.U.T. continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the D.U.T. stops triggering. τ_{RC} is measured at this point and recorded.



* This optoisolator should not be used to drive a load directly. It is intended to be a trigger device only.

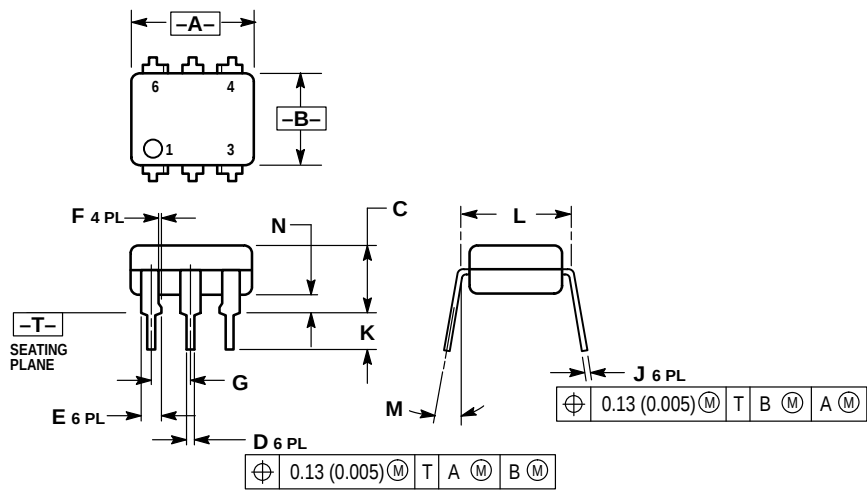
Additional information on the use of optically coupled triac drivers is available in Application Note AN-780A.

In this circuit the "hot" side of the line is switched and the load connected to the cold or ground side.

The 39 ohm resistor and 0.01 μ F capacitor are for snubbing of the triac, and the 470 ohm resistor and 0.05 μ F capacitor are for snubbing the coupler. These components may or may not be necessary depending upon the particular triac and load used.

Figure 8. Typical Application Circuit

PACKAGE DIMENSIONS

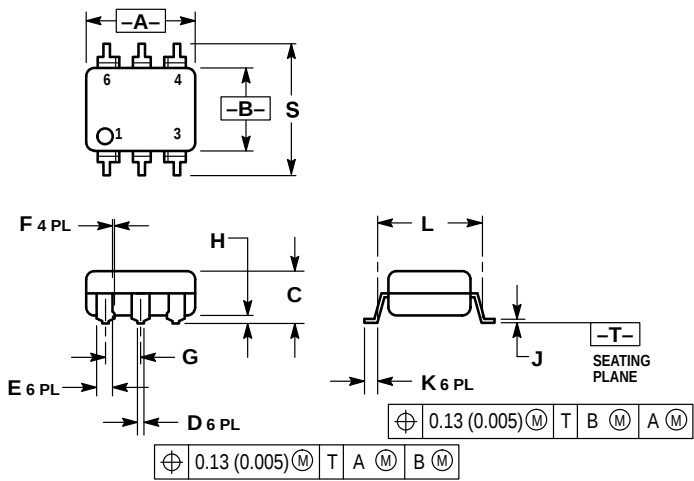


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.320	0.350	8.13	8.89
B	0.240	0.260	6.10	6.60
C	0.115	0.200	2.93	5.08
D	0.016	0.020	0.41	0.50
E	0.040	0.070	1.02	1.77
F	0.010	0.014	0.25	0.36
G	0.100 BSC		2.54 BSC	
J	0.008	0.012	0.21	0.30
K	0.100	0.150	2.54	3.81
L	0.300 BSC		7.62 BSC	
M	0 °	15 °	0 °	15 °
N	0.015	0.100	0.38	2.54

- STYLE 6:
- PIN 1. ANODE
 - CATHODE
 - NC
 - MAIN TERMINAL
 - SUBSTRATE
 - MAIN TERMINAL

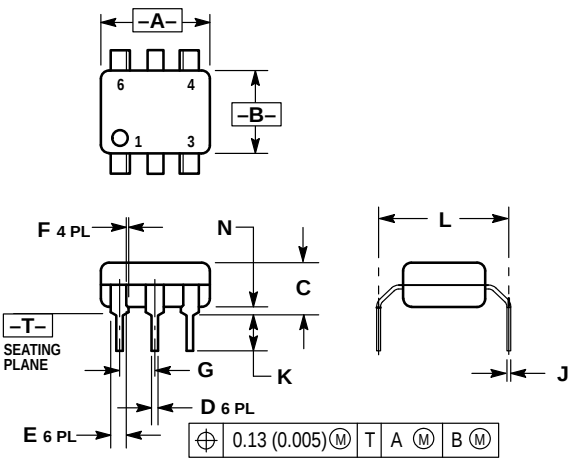
THRU HOLE



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C	0.115	0.200	2.93	5.08
D	0.016	0.020	0.41	0.50
E	0.040	0.070	1.02	1.77
F	0.010	0.014	0.25	0.36
G	0.100 BSC		2.54 BSC	
H	0.020	0.025	0.51	0.63
J	0.008	0.012	0.20	0.30
K	0.006	0.035	0.16	0.88
L	0.320 BSC		8.13 BSC	
S	0.332	0.390	8.43	9.90

SURFACE MOUNT



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B	0.240	0.260	6.10	6.60
C	0.115	0.200	2.93	5.08
D	0.016	0.020	0.41	0.50
E	0.040	0.070	1.02	1.77
F	0.010	0.014	0.25	0.36
G	0.100	BSC	2.54	BSC
J	0.008	0.012	0.21	0.30
K	0.100	0.150	2.54	3.81
L	0.400	0.425	10.16	10.80
N	0.015	0.040	0.38	1.02

0.4" LEAD SPACING

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